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Signed: Vickie Ishimaru
Vickie Ishimaru



Docket No.: 27-035.D1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	John Briar	:	Confirmation No.:	2274
Serial No.:	10/693,217	:	Art Unit:	2811
Filed:	October 24, 2003	:	Examiner:	Douglas W. Owens
For:	FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE STRUCTURE	:		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**SUPPLEMENTAL PRELIMINARY AMENDMENT
UNDER 37 CFR §1.115**

Sir:

The following Preliminary Amendment is submitted for Divisional patent application number 10/693,217 before the first Office action under 37 CFR §1.104 and is supplemental to the Preliminary Amendment filed with the application on October 24, 2003, following the procedures set forth in 37 CFR §1.121.

After this introductory section there are Amendments to the Drawings and then Remarks, each starting on a separate page.

Drawing amendments consist of Amendments to FIG. 1, FIG. 2, and FIG. 3.

AMENDMENTS TO THE DRAWINGS

Please amend FIG. 1, FIG. 2, and FIG. 3 of the drawings as shown on the replacement page which follows. The amended part is discussed in the Remarks section, and a marked up version to show changes is included in Appendix A.